

REMARKS

Claims 1-14 are pending in this application. Independent claims 1, 5 and 10 have been amended above. As to the amendments, see, e.g., Applicants' figures.

For appreciating the present invention, one embodiment may be considered, namely, providing an aperture 14 in a package 13 on which the photodetector array 11 is directly mounted, as discussed in the Applicants' specification at page 5, lines 9-11, with reference to the figures of this application. Such a construction is not disclosed in the cited references, Ford (USP 6,307,657) and Grann (USP 6,563,976). By providing the aperture on the package, the device advantageously can be down-sized.

At page 2 of the office action, Claims 1-9 have been rejected under 35 U.S.C. 102(e) as being anticipated by Ford (US 6,307,657).

Applicants respectfully traverse the anticipation rejection based on Ford, as mentioned above and as follows.

Applicants' Claim 1 recites a light-sensitive detector comprising "a photodetector which is formed in a semiconductor chip" and "a package on which said semiconductor chip is directly mounted." Ford fails to teach or disclose a package, as claimed, on which a semiconductor chip is directly mounted, with the feature, as claimed, of "a photodetector which is formed in a semiconductor chip." Rather, by contrast, the package 802 in Ford is on the device mount 801.

For at least the reasons set forth above, Applicants' presently claimed invention is distinguished from Ford. Reconsideration and withdrawal of the anticipation rejection based on Ford are respectfully requested.

At page 3 of the office action, Claims 10-14 have been rejected under 35 U.S.C. 102(e) as being anticipated by Grann et al. (US 6,563,976). The Examiner particularly cites Fig. 16 of Grann.

Applicants respectfully traverse the anticipation rejection based on Grann, as mentioned above and as follows. In Grann, there is no intention to downsize the device.

In Applicants' claim 10, the light-sensitive detector comprises "at least one photodetector which is formed in a semiconductor chip, and said semiconductor chip .. sealingly disposed within said package." Grann fails to teach providing a semiconductor chip directly on a package.

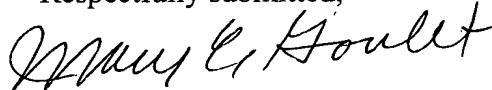
For at least the reasons set forth above, Applicants' presently claimed invention is distinguished from Grann. Reconsideration and withdrawal of the anticipation rejection based on Grann are respectfully requested.

In view of the foregoing, it is respectfully requested that the application be reconsidered, that claims 1-14 be allowed, and that the application be passed to issue.

Should the Examiner find the application to be other than in condition for allowance, the Examiner is requested to contact the undersigned at the local telephone number listed below to discuss any other changes deemed necessary in a telephone or personal interview.

A provisional petition is hereby made for any extension of time necessary for the continued pendency during the life of this application. Please charge any fees for such provisional petition and any deficiencies in fees and credit any overpayment of fees to Attorney's Deposit Account No. 50-2041.

Respectfully submitted,



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